

17th International Workshop on the Physics of Semiconductor Devices 2013



## **Environmental Science and Engineering**

## **Environmental Engineering**

Series Editors

Ulrich Förstner, Hamburg, Germany Robert J. Murphy, Tampa, USA W. H. Rulkens, Wageningen, The Netherlands V. K. Jain • Abhishek Verma Editors

# Physics of Semiconductor Devices

17th International Workshop on the Physics of Semiconductor Devices 2013



Editors
V. K. Jain
Abhishek Verma
Amity Institute for Advanced Research
and Studies (Meterials & Devices)
Amity University
Noida, Uttar Pradesh
India

ISSN 1863-5520 ISSN 1863-5539 (electronic) ISBN 978-3-319-03001-2 ISBN 978-3-319-03002-9 (eBook) DOI 10.1007/978-3-319-03002-9

Springer Cham Heidelberg New York Dordrecht London

## Library of Congress Control Number: 2013953611 © Springer International Publishing Switzerland 2014

This work is subject to copyright. All rights are reserved by the Publisher, whether the whole or part of the material is concerned, specifically the rights of translation, reprinting, reuse of illustrations, recitation, broadcasting, reproduction on microfilms or in any other physical way, and transmission or information storage and retrieval, electronic adaptation, computer software, or by similar or dissimilar methodology now known or hereafter developed. Exempted from this legal reservation are brief excerpts in connection with reviews or scholarly analysis or material supplied specifically for the purpose of being entered and executed on a computer system, for exclusive use by the purchaser of the work. Duplication of this publication or parts thereof is permitted only under the provisions of the Copyright Law of the Publisher's location, in its current version, and permission for use must always be obtained from Springer. Permissions for use may be obtained through RightsLink at the Copyright Clearance Center. Violations are liable to prosecution under the respective Copyright Law.

The use of general descriptive names, registered names, trademarks, service marks, etc. in this publication does not imply, even in the absence of a specific statement, that such names are exempt from the relevant protective laws and regulations and therefore free for general use.

While the advice and information in this book are believed to be true and accurate at the date of publication, neither the authors nor the editors nor the publisher can accept any legal responsibility for any errors or omissions that may be made. The publisher makes no warranty, express or implied, with respect to the material contained herein.

Printed on acid-free paper

Springer is part of Springer Science+Business Media (www.springer.com)

### **Preface**

Science and technology of twenty-first century is relying heavily on the development of new materials and their structures. In which the technology of semiconductors is the foundation of modern electronics, including transistors, solar cells, light-emitting diodes (LEDs), quantum dots, and digital and analog integrated circuits. The various fields of semiconductor have continued to prosper and to break new ground. This development has been so fast and may even impact our environment, like by decreasing the amount of fossil fuel used to produce electricity. Therefore, any sort of updated research, latest findings in the area related to semiconductor must be important to all scientific community. The history of the understanding of semiconductors begin with experiments on electrical properties of materials. The properties of negative temperature coefficient of resistance, rectification, and light sensitivity were observed in the early nineteenth century. Since then, a wide variety of techniques were used and discovered to analyze the properties of semiconductors, more than 300 billion dollar sector of the world's economy that designs and manufactures semiconductor devices and many Nobel Prizes have been given in the field of semiconductors. Still, all over the world very intensive work is going on different technologies based on thrust areas of this workshop, and it is essential to keep abreast with the latest developments in advanced fabrication techniques, characterization tools, and also in understanding the physics to enable and produce reliable large volume production of state-of-the-art devices.

About the futuristic optoelectronics, it can be quoted the T. Hiruma's vision that "detecting a single photon cannot be the end point. It is just a starting point. Human kind doesn't know enough even in photonics. We have to find our own direction. God of absolute truth. In-fact we are able to detect a single photon now using a low noise detectors. We have been measuring light from the human body. The body emits about 100 photons per second. His question at the moment is how to measure wavelength and polarity of this light. The purpose is to explore way to apply these photon technologies to study biology and brain."

Now, it's an era of nanotechnology, which can be regarded as the major technological challenge of this century that is stirring people's imagination about its potential use. A new era has already begun, which is changing people's way of life, thinking, and behavior in a very deep manner. Nano scientists can even manipulate objects and forces at the nano scale. At this size, matter behaves differently, light and electricity resolve into individual photons and electrons, particles pop in and out of existence, and other once theoretical oddities of quantum mechanics are seen to be real. Therefore, to give a full exposure and new platform to young scientists and researchers, along with face-to-face discussion with top scientists of particular area, this type of International workshop will highly be beneficial.

The book *Physics of Semiconductor Devices* comprises of scientific contributions from different veins of semiconductor materials, devices, and the related technologies. The

vi Preface

contribution has been made by different researchers and eminent scientist from all over the world who presented their paper in the seventeenth International Workshop on the Physics of Semiconductor Devices, 2013 organized by Amity University, Noida. The purpose and objective of this meeting is to spread the vast knowledge of semiconductor physics in every possible field for academia and industry. Through this, every latest finding, research and discovery can go ahead to our scientific world. The chapters include various latest and significant topics, i.e., Optoelectronics, VLSI and ULSI Technology, Photovoltaics, MEMS and Sensors, Device Modeling and Simulation, High Frequency/Power Devices, Nanotechnology and Emerging Areas, Display and Lighting, and Organic Electronics.

The editors wish to place on record our appreciation to Dr. Ashok K. Chauhan, Founder President, Amity University, Noida for his encouragement. Our sincere gratitude goes to Dr. Prashant Shukla, Dr. Abhishek Kardam, Dr. S. S. Narayanan, Dr. Devinder Madhwal, and all the members of seventeenth International Workshop on the Physics of Semiconductor Devices, 2013 for their help in organizing this workshop.

V. K. Jain Abhishek Verma

## **Contents**

#### Section A

	Part I	VLSI	and	<b>ULSI</b>	<b>Technolog</b>
--	--------	------	-----	-------------	------------------

Impact of Fin Sidewall Taper Angle on Sub-14 nm FinFET	
Device Performance	3
E. J. Nowak and Kota V. Murali	
Capacitance-Voltage Measurement of SiO <sub>2</sub> /GeO <sub>x</sub> N <sub>y</sub> Gate Stack on Surface Passivated Germanium	5
Anil G. Khairnar, Vilas S. Patil and Ashok M. Mahajan	3
Effect of Supercritical Drying on Sol-Gel Deposited Silica Aerogel  Thin Films at Different Temperatures	9
Anil Gaikwad, Yogesh Mhaisagar, Jigar Bhavsar and Ashok Mahajan	
Stress-induced Degradation and Defect Studies	1.0
In Strained-Si/SiGe MOSFETs	13
Co-existence of Multiferroic Memories in CoFe <sub>2</sub> O <sub>4</sub> /Bi <sub>3.4</sub> Sm <sub>0.6</sub> Ti <sub>3</sub> O <sub>12</sub>	17
Composite Structures	1 /
Γ-CAD Design Simulation and Comparative Performance Analysis of 6-T SRAM Cell with Nanoscale SOI and MOS Technology	21
P. Deepika, E. Subhasri and Sanjoy Deb	21
Investigation of Current Conduction Mechanism in HfO <sub>2</sub> Thin Film	2.5
on Silicon Substrate	25
Resistive Switching in MIM Capacitors Using Porous Anodic Alumina	29
K. Mukherjee, S. Upreti, A. Bag, S. Mallik, M. Palit, S. Chattopadhyay and C. K. Maiti	
Process Model Accuracy Enhancement Using Cluster Based Approach	33
Pardeep Kumar, Samit Barai, Babji Srinivasan and Nihar R. Mohapatra	

viii Contents

Room Temperature-Processed TiO <sub>2</sub> MIM Capacitors for DRAM Applications	37
Revathy Padmanabhan, Navakanta Bhat and S. Mohan	
Two Input Multiplexer Based on Single-Electronics	41
Part II High Frequency and Power Devices	
Advancements in SiC Power Devices Using Novel Interface Passivation Processes.  Y. K. Sharma, A. C. Ahyi, T. Issacs-Smith, A. Modic, Y. Xu, E. Garfunkel, M. R. Jennings, C. Fisher, S. M. Thomas, L. Fan, P. Mawby, S. Dhar, L. C. Feldman and J. R. Williams	47
Planar Schottky Varactor Diode Characterization for MMIC Voltage	
Controlled Oscillator Applications	53
Optically-Switched Wide-Bandgap Power Semiconductor Devices and Device-Transition Control	57
Study on Temperature Dependence Scattering Mechanisms and Mobility Effects in GaN and GaAs HEMTs	67
Study of Oxygen Implantation in GaN/Sapphire	71
GaN HEMT Based S-Band Power Amplifier	75
Structural and Optical Characterization of β-Ga <sub>2</sub> O <sub>3</sub> Thin Films Grown by Pulsed Laser Deposition	77
Effect of Vertical and Longitudinal Electric Field on 2DEG of AlGaN/GaN HEMT on Silicon: A Qualitative Reliability Study	81
Electrical Characterization of Interface States in In/p-Si Schottky  Diode From I–V Characteristics	85
Temperature Dependence Junction Parameters: Schottky Barrier, Flatband Barrier, and Temperature Coefficients of Schottky Diode	89

<u>Contents</u> ix

of AlGaN/GaN Based HEMT Using Electrical Measurement	91
Effect of Junction Temperature on the Microwave Properties of IMPATT Diodes	95
On the Determination of Electron Effective Mass in 2DEGs in Gallium Nitride HEMT Structures	99
Observation of Negative Magnetoresistance in Gallium Nitride HEMT Structures	103
Large-Signal Analysis of III-V Nitride Based DD-Transit Time Device:  A New Source for THz Power Generation	107
A Comparison of Hot Carrier and 50 MeV Li <sup>3+</sup> Ion Induced Degradation in the Electrical Characteristics of Advanced 200 GHz SiGe HBT K. C. Praveen, N. Pushpa, M. N. Bharathi, John D. Cressler and A. P. Gnana Prakash	113
Growth and Characterization of AlInGaN/AlN/GaN Grown by MOCVD Ravi Loganathan, Mathaiyan Jayasakthi, Kandhasamy Prabakaran, Raju Ramesh, Ponnusamy Arivazhagan, Boopathi kuppulingam, Subramanian Sankaranarayanan, Manavaimaran Balaji, Shubra Singh and Krishnan Baskar	117
Structural Optical and Electrical Studies of AlGaN/GaN Hetrostructures with AlN Interlayer Grown on Sapphire Substrate by MOCVD Raju Ramesh, Ponnusamy Arivazhagan, Mathiyan Jayasakthi, Ravi Loganthan, Kandhasamy Prabakaran, Boopathi Kuppuligam, Manavimaran Balaji and Krishnan Baskar	119
Effect of Ni Ions Irradiation on GaAs pHEMT Materials and Devices Rupesh K. Chaubey, Akhilesh Pandey, A. A. Naik, Seema Vinayak, B. K. Sehgal and P. C. Srivastava	121
Design and Fabrication of GaN HEMT Based Power Amplifier	125
Electron Beam Lithography for Fabrication of Sub 250 nm T Gates for AlGaAs/InGaAs PHEMT Based MMICs	127
L Band to 140 MHz Frequency Converter for Wide Dynamic Range Receiver	131

x Contents

Ohmic contacts to AlGaN/GaN HEMTs: A Comparison of Two Different Ti/Al Metaletal Ratios	133
Somna S. Mahajan, Robert Laishram, Sonalee Kapoor, Anshu Goel, Seema Vinayak and B. K. Sehgal	
Development of GaAs Hyperabrupt Schottky Varactor Diode using Ion-Implanted Active Layer on SI GaAs	137
S. Dayal, S. Mahajan, D. S. Rawal and B. K Sehgal	
Passivation of AlGaN/GaN HEMT by Silicon Nitride	141
Gate Leakage Current Suppression in AlGaN/GaN HEMT	
by RTP Annealing.  Somna S. Mahajan, Anushree Tomar, Robert Laishram, Sonalee Kapoor, Amit Mailk, A. A. Naik, Seema Vinayak and B. K. Sehgal	145
A Method to Characterize Microstrip Lines for Design of MMICs	
up to 40 GHz	149
Small-Signal RF and Microwave Characteristics of Sub-Micron	
AlGaN/GaN HEMT  T. R. Lenka, G. N. Dash and A. K. Panda	153
Design and Development of an S-band 6 bit MMIC Attenuator with Low Insertion Loss	157
Part III Device Modelling and Simulation	
Monitoring Parameters for Optimization of Power & Efficiency	1.60
and Minimization of Noise in High Frequency IMPATT Diodes S. P. Pati and P. R. Tripathy	163
<b>Bipolar Attributes of Unipolar Junctionless MOSFETs</b>	169
Ambipolar Behaviour of Tunnel Field Effect Transistor (TFET)	
as an Advantage for Biosensing Applications	171
Analytical Expression of Barrier Layer for Enhancement Mode AlGaN/GaN HEMT	175
Apurba Chakraborty, Saptarshi Ghosh, Ankush Bag, Palash Das and Dhrubes Biswas	
Modeling and Simulation of Package Inductance for Pulsed IMPATT Diodes with Integrated Beam Lead Structure	179
Arijit Das, Diptadip Chakraborty and Nabin Chandra Mandal	117

<u>Contents</u> xi

Memristor-based Memory Cell with Less Noise Margins and Storing Non-Binary Data	183
B. K. Das	
Reduction of Electron Overflow Problem by Improved InGaN/GaN Based Multiple Quantum Well LEDs Structure with p- AlInGaN/AlGaN EBL Layer	189
Dipika Robidas and D Arivuoli	
Two Dimensional Model for Threshold Voltage Roll-Off of Short Channel High-k Gate-Stack Double-Gate (DG) MOSFETs	193
A Quantum Analytical Model for Inversion Current in Short Channel	
DMDG SON MOSFET  Gargee Bhattacharyya, Sharmistha Shee, Pranab Kishore Dutta and Subir Kumar Sarkar	197
An Analytical Study of Ion Implanted Strained-Si on SOI MOSFETs for Optimizing Switching Characteristics	203
Statistical Compact Model Extraction for Skewed Gaussian Variations V. Janakiraman, Shrinivas J. Pandharpure and Josef Watts	207
On the Voltage Transfer Characteristics (VTC) of some Nanoscale Metal-Oxide-Semiconductor Field-Effect-Transistors (MOSFETs) Jhuma Saha, Amrita Kumari, Shankaranand Jha and Subindu Kumar	211
Influence of Interface Deep Traps on Capacitance of AlGaN/GaN Heterojunctions	215
Effect of Ge-composition on the Gain of a Thin Layer Si <sub>1-y</sub> Ge <sub>y</sub> Avalanche Photodiode	219
Prformance Investigation of Dual Material Gate Stack Schottky-Barrier Source/Drain GAA MOSFET for Analog Applications	223
Large Signal Physical Operation of a III–V Nitride Based Double Velocity Transit Time Device: A Potential Source For THz Imaging	225
Influence of Source-Gate and Gate Lengths Variations on GaN HEMTs  Based Biosensor	229
Effect of Intersubband Interaction on Multisubband Electron Mobility in a Parabolic Quantum Well Under Applied Electric Field N. Sahoo, A. K. Panda and T. Sahu	231

xii Contents

Prospects and issues of Diamond based IMPATT Diode at MM-Wave Frequency	235
P. R. Tripathy, M. Mukherjee, S. K. Choudhury and S. P. Pati	
The Application of Level Set Method for Simulation of PECVD/LPCVD Processes	239
Sajai Sagai Singii, Tuan Ei, Tan Aing and Hein Fai	
Doping Concentration Dependence of Pinch-Off Effect in Inhomogeneous Schottky Diodes	243
Gate Leakage Current Modeling in Ferroelectric FET	247
A New Superjunction Power MOSFET with Oxide-Pillar-in-Drift Region Deepti Sharma and Rakesh Vaid	251
Electron mobility Enhancement in Barrier Delta Doped Asymmetric  Double Quantum Well Structures  S. Das, R. K. Nayak, T. Sahu and A. K. Panda	255
A Simplified Approach for Automatic Extraction of Model Parameters of Spiral Inductors for Design of MMICs	259
Threshold Voltage Modeling of Short-Channel DG MOSFETs with Non-Uniform Doping in the Vertical Direction	263
Improved Underlap FinFET with Asymmetric Spacer Permittivities Saurabh K. Nema, M. SaiKiran, P. Singh, Archana Pandey, S. K. Manhas, A. K. Saxena and Anand Bulusu	267
Comprehensive Analytical Modeling of N-polar GaN/AlGaN Insulated Gate HEMTs with and without Polarization Neutralization Layer Saptarsi Ghosh, Syed Mukulika Dinara, Ankush Bag, Apurba. chakraborty, Partha Mukhopadhyay, Sanjib Kabi and Dhrubes Biswas	269
Microwave Characteristics of SiC IMPATT Diodes at 220 GHz S. R. Pattanaik, J. Pradhan, S. K. Swain and G. N. Dash	273
Spectral Peak Shift in One-Dimensional Nonlinear Photonic Crystal	277
Investigation on Hybrid Green Light-Emitting Diode	281
Advanced AlGaN/GaN Resonant Tunneling Diode on Silicon Substrate for Negligible Scattering and Polarization effects	285

Contents

Improved Performance of Junctionless Tunnel FETs with Source/Channel Heterostructure	289
Modeling Charge Control in Heterostructure Nanoscale Transistors	291
Surface Potential Based Analytical Model for Hetero-Dielectric p-n-i-n Double-Gate Tunnel-FET	295
Hot Carrier Reliability Issues of Junctionless Transistor due to Interface Trap Charges for Analog/RF Applications	299
Section B	
Part IV Photovolatics	
Tuning of Plasmonic Nanoparticles for Enhancing Solar Cell Efficiency Somik Chakravarty, Lingeswaran Arunagiri, Shiv Chaudhary, Abhishek Verma and V. K. Jain	305
Enhancement of Performance of Crystalline and Amorphous Silicon Solar Cells through Optical Engineering by Nanostructured Materials H. Saha and Swapan K. Datta	309
Single-Pot Rapid Synthesis of Colloidal Core/Core-Shell Quantum Dots:  A Novel Polymer-Nanocrystal Hybrid Material	315
Study of Al and Ga Doped and Co-Doped ZnO Thin Film as front Contact in CIGS Solar Cell	319
Charge Transport Studies in Pure and CdS Doped PBDTTPD: CdS Nanocomposite for Solar Cell Application	323
Encapsulation of SiNWs Array with Diamond-like Nanocomposite Thin Film for Ultra-low Reflection	327
In-Situ Growth of CdS Nanorods in PTB7 by Solvothermal Process for Hybrid Organic Inorganic Solar Cell applications	331

xiv Contents

Synthesis of AgInS <sub>2</sub> Nanoparticles Directly in Poly (3-hexyl thiophene) (P3HT)Matrix: Photoluminescence Quenching Studies	335
Role of Plane and Textured TCO Surfaces in Enhancing the Efficiency of Thin Film Amorphous Silicon Solar cell: A Theoretical Approach	339
Thermal Sintering Improves the Short Circuit Current of Solar Cells Sensitized with CdTe/CdSe Core/Shell Nanocrystals	343
Effect of Cd/S Molar Ratio on the Optical and Electrical Properties of Spray Deposited CdS Thin Films	347
Comparison of Incorporation of Na via In-situ and Ex-situ Modes for the Realization of Device Quality CIGSe Thin Films	351
A Method of Estimating Indium Bump Integration Yield in Hybrid IRFPA of HgCdTe Photodiodes	355
Current-Voltage and Capacitance-Voltage Characteristics of Ni/p-Si (100) Schottky Diode Over a Wide Temperature Range	359
Effect of Substrate Temperature on the Structural and Optical Properties of CdTe Films Prepared by Thermal Evaporation	363
Study of Schottky Barrier Contact in Hybrid CdSe Quantum Dot Organic Solar Cells	367
Measurement of Variation of Minority Carrier Lifetime in 8 MeV Electron Irradiated c-Si Solar Cells Using RRT Method	371
Front Surface Glass Texturization for Improved Performance of Amorphous Silicon Solar Cell	375
Study of Light-Induced Structural Changes Associated with Staebler-Wronski Photo-Degradation in Micro-Crystalline Silicon Thin Films Sucheta Juneja, S. Sudhakar, Kalpana Lodhi, Srishti Chugh, Mansi Sharma and Sushil Kumar	379

Contents xv

Phosphorous Doped Hydrogenated Amorphous Silicon Carbide Films	
Deposited by Filtered Cathodic Vacuum Arc Technique	383
Silicon Surface Passivation by Al <sub>2</sub> O <sub>3</sub> film using Atomic Layer Deposition P. K. Singh, Vandana, Neha Batra, Jhuma Gope, CMS Rauthan, Mukul Sharma, Ritu Srivastava, S. K. Srivastava and P. Pathi	387
Estimation of Photovoltaic Cells Model Parameters using Particle	
Swarm Optimization	391
Sustainable Organic Polymer Solar Cells Using TiO <sub>2</sub> Derived From	
Automobile Paint Sludge	395
CIGS thin film Deposition by Dual Ion Beam Sputtering (DIBS) system	
for Solar cell Applications	399
Section C	
Part V MEMS and Sensors	
Study of Fluid Flow in Micro-channel Based Devices	405
Graphite Based Sensor for LPG and CO Detection	409
Development of Lactate Biosensor Based on Electro Statically Functionalized Graphene Oxide Bound Lactate Oxidase  Meeta Gera, V. K. Jain and N. Suman	413
Humidity Sensing Response of Poly (3, 4-ethylene dioxythiophene)-poly (styrene sulphonate) and Its Nanocomposites	417
PECVD Grown SiC Cantilevers with Dry and Wet Release  Adithi Umamaheswara, Smitha Nair, Lavendra, Suman Gupta,  M. N. Vijayaraghavan and Navakanta Bhat	421
MEMS Mirrors for Optical Switching Applications	425
Design Aspects of a MEMS Based Bi-axial Mirror	429

xvi Contents

Electrochemical Synthesis of p-CuO Thin Films and Development of a p-CuO/n-ZnO Thin Film Hetero-Contact for Gas Sensing	433
Optical Characterization of Anodically Grown Silicon Dioxide Thin Films Ashok Akarapu and Prem Pal	437
Study on Design and Simulation of Zinc Oxide Based Film Bulk Acoustic Resonator for RF Filters	441
Design and Analysis of RF MEMS Shunt Capacitive Switch for Low Actuation Voltage and High Capacitance Ratio	445
Design and Development of MEMS Pressure Sensor Characterization Setup with Low Interfacing Noise by Using NI-PXI System	449
Ag–ZnO Nanocomposite for Multi Gas Sensing Applications	453
Effect of Cu <sub>3</sub> N Layer Thickness on Corrosion and Ni Release Properties of Cu <sub>3</sub> N/NiTiCu Shape Memory Thin Films	457
<b>Design of a Piezoresistive MEMS Resonator Operating Beyond 1 GHz</b> Vikrama Vamshi Pasula, Deleep R. Nair and Amitava DasGupta	461
A Novel Test Structure for Testing of ROIC for 2D Bolometric IR FPA Raghvendra Sahai Saxena, Sushil Kumar Semwal, Nilima Singh and R. K. Bhan	465
Thick PECVD Germanium Films for MEMS Application	469
Design and Fabrication of Wafer-Level Package for RF MEMS Switch Using BCB	473
Anisotropy and Surface Roughness of Silicon Etched by TMAH in Presence of Potassium Persulfate: A Comparison with Ammonium Persulfate	475
A Novel Room Temperature Ammonia Gas Sensor Based on Diamond-Like Nanocomposite/c-Silicon Heterojunction	479
Fabrication of High Density Silicon Microprobe Array	483

Contents xvii

Study of PDMS as Dielectric Layer in Electrowetting Devices	487
Stress Engineering Using $Si_3N_4$ for Stiction Free Release of SOI Beams Suman A. Gupta, Apoorva Shenoy, Monisha, V. Uma, M. N. Vijayaraghavan and Navakanta Bhat	491
Comparative Study on Temperature Coefficient of Resistance (TCR) of the E-beam and Sputter Deposited Nichrome Thin Film for Precise Temperature Control of Microheater for MEMS Gas Sensor	495
Enhanced TCR with Room Temperature T <sub>MI</sub> for Potential  Application in Microbolometer	499
High Resolution Quadrant Detector Based Tip-tilt Sensor for Adaptive Optics	503
Section D	
Part VI Nanotechnology and Emerging Areas	
Raman Spectroscopy and Molecular Dynamics Simulation Studies of Carbon Nanotubes	507
Equilibrium and Nonequilibrium Carrier Statistics in Carbon Nano-Allotropes	511
Power Generation Using Graphene and Silver Nano Composite Based Paper Battery	517
Study of Forster's Resonance Energy Transfer Between MWCNT and Phenoxazone 660	521
How to Achieve High Quality Large Area Monolayer Graphene with Field Effect Mobility of 20,000 cm²/Vs	523
Field-Emission Study of Carbon Nanotubes Grown by Low Pressure Chemical Vapour Deposition on Single and Dual Layer of Catalyst	527
A Novel Nanographite Based Non-enzymatic Cholesterol Sensor	531

xviii Contents

Electron Beam Lithography Patterning of 50 nm Trenches and Islands on PMMA	535
S. S. Sarkar, A. Rudra, R. K. Khatri and R. Muralidharan	555
Lattice Specific Heat of Graphene Nanoribbons	539
Catalytic Growth of 3C-SiC Nanorods: Structural and Optical Characterization	543
Synthesis and Characterization of Phosphorus Doped Hydrogenated Silicon Films by Filtered Cathodic Vacuum Arc Technique Ajay Kesarwani, O. S. Panwar, R. K. Tripathi and Sreekumar Chockalingam	547
Room Temperature Ferromagnetism in ZnO Using Non-magnetic Ions  Zaheer Ahmed Khan, Anshu and Subhasis Ghosh	551
Stress Induced Degradation in Sputtered ZrO <sub>2</sub> Thin Films on Silicon for Nano-MOSFET's	555
Synthesis of Vertical Graphene by Microwave Plasma Enhanced Chemical Vapor Deposition Technique	559
Raman Characteristics of Vertically Aligned Single Wall Carbon Nanotubes Grown by Plasma Enhanced Chemical Vapor Deposition System	563
A Novel of Synthesis of Iron Oxide Nanoparticles for Separation of Water-Oil, Water-Diesel, Water-Petrol	565
Electrical Characteristics of SWCNT Chemiresistor	569
Studies on Nanostructured $V_2O_5$ Deposited by Reactive DC Magnetron Sputtering	573
Surface Enhanced Raman Scattering on Anodized Alumina Templates for Bio-sensing Applications	577
Impact of Scaling Gate Oxide Thickness on the Performance of Silicon  Based Triple Gate Rectangular Nwfet  Deepika Jamwal, Devi Dass, Rakesh Prasher and Rakesh Vaid	581

<u>Contents</u> xix

Characterization of Carbon Nanotube Field Effect Transistor Using Simulation Approach	585
Electrical Characterization of n-ZnO Nanowires/p-Si Based Heterojunction Diodes	589
Chalcogenide Micro/Nanostructures by Evaporation Condensation Method Swati Raman, Ravi K. Kumar and M. Husain	593
Structural and Optical Characterization of ZnO Nanoparticles Synthesized Via Low Temperature Precipitation Method	597
Synthesis and Optical Properties of Pure and Eu <sup>+3</sup> Ion Doped ZnO Nanoparticles Prepared Via Sol-Gel Method	599
Synthesis of CNTs by Arc Discharge Method in Water Bath	601
Comparative Study of SWNTs Dispersion in Organic Solvent and Surfactant Along with Observation of Multilayer Graphene	603
Hydrothermal Growth and Characterization of ZnO Nanomaterials Shashidhara Bhat, B. V. Shrisha and K. Gopalakrishna Naik	607
Grafting of Ag Nanoparticles on GO Nano Sheets for Water Purification Jimmy Mangalam and Monika Joshi	611
Effect of ZnO Loading on the Electrical Characteristics of Graphene Oxide-ZnO Based Thin Film Transistors	615
Lattice Thermal Conductivity of Silicene	617
Gas Sensing Properties of Tin Oxide Nano-Powder Synthesized via Sol-Gel Route	621
Structural and Optical Studies of Sol–Gel Deposited Nanostructured ZnO Thin Films: Annealing Effect	625
Design of 2D Photonic Crystals for Integrated Optical Slow-Light Applications	631

xx Contents

Morphological and Optical Studies of Electrodeposited Selenium Nanowires Narinder Kumar, Rajesh Kumar, Sushil Kumar and S. K. Chakarvarti	633
Effect of Metal Contact on CNT Based Sensing of NO <sub>2</sub> Molecules	637
Synthesis of Zinc Oxide Nanostructures by Chemical Routes Nidhi Gupta, Omita Nanda, Pramod Kumar, V. K. Jain and Kanchan Saxena	641
Effect of Growth Temperature on the Diameter Distribution and Yield of Carbon Nanotubes	645
Growth and Characterization of MOCVD grown InP Quantum  Dots on Si for Monolithic Integration	647
Synthesis of Multilayer Graphene by Filtered Cathodic Vacuum Arc Technique	651
Role of Coherent Nanostructures and Mass Fluctuation on Thermoelectric Properties in Iodine Doped PbTe $_{0.5}$ Se $_{0.5}$	655
Structural and Elastic Properties of $Cd_{1-x}Ni_xFe_2O_4$ Ferrites P. B. Belavi and L. R. Naik	659
Investigations on: How the Band Lineups, Band Offsets and Photoluminescences of an $In_xGa_{1-x}N/GaN$ Quantum Well change with Biaxial Strain	663
Effect of Dielectric Environment on Carrier Mobility in Chemically Exfoliated Graphene	667
Fabrication of SWCNTs Based Flexible, Trace Level NO <sub>2</sub> Gas Sensor Using Spray Coating Technique	669
Growing Monolayer, Bilayer and Trilayer Reproducibly  By Chemical Exfoliation	671
Electrical Characteristics of Si/ZnO Core–Shell Nanowire  Heterojunction Diode	673

Contents xxi

Novel Attributes in Scaling Issues of an InSb-Nanowire Field-Effect Transistor	677
Rakesh Prasher, Devi Dass and Rakesh Vaid	
Inductively Coupled Plasma Etching of GaAs with High Anisotropy for Photonics Applications	681
Growth and Characterization of Nitrogen Incorporated Amorphous Carbon Films Having Embedded Nanocrystallies	685
Impact of Silicon Body Thickness on the Performance of Gate-all-around Silicon Nanowire Field Effect Transistor	689
Room Temperature Synthesis of Al:ZnO Quantum Dots	693
Phonon-limited Diffusion Thermopower in Graphene	695
Humidity Sensing by Chemically Reduced Graphene Oxide	699
<b>Toxicity Study of TiO<sub>2</sub>, ZnO and CNT Nanomaterials</b>	703
Synthesis and Characterization of Zinc Oxide Nanoparticles for Ethanol Detection	707
Structural and Optical Studies of Sol-Gel Deposited Nanostructured ZnO Thin Films: Annealing Effect	709
Gold Catalyzed Plasma Assisted Growth of Germanium Nanoneedles Sangeeth Kallatt, Smitha Nair, M. N. Vijayaraghavan and Navakanta Bhat	713
Studies on Structural Parameters of ZrO <sub>2</sub> –SnO <sub>2</sub> Binary System	717
Nano Lithium Iron Phosphate Cathode Material for Li-ion Based Batteries for Underwater Applications	721
Porous Anodic Alumina Template Formation: Deposition Technique Dependence	725

xxii Contents

Synthesis and Characterization of CuO-TiO <sub>2</sub> Core Shell Nanocomposites for Hydrogen Generation Via Photoelectrochemical Splitting of Water Shailja Sharma, Babita Kumari, Nirupama Singh, Anuradha Verma, Vibha R. Satsangi, Sahab Dass and Rohit Shrivastav	729
Highly Efficient Field Emission Characteristics of Ultra-long Vertical Aligned Single Wall Carbon Nanotubes	733
Temperature Dependence Thermal Conductivity of ZnS/PMMA Nanocomposite	737
Nanoindentation Study of Mechanical Properties of Diamond Like Carbon Coatings S. Chockalingam, R. K. Tripathi and O. S. Panwar	741
Fabrication of Vertically Aligned Carbon Nanotubes on MgO Support Layer by Thermal Chemical Vapor Deposition for Field Emission Application	745
Thermal Evolution of Mixed Oxides of Zirconia-Silica Prepared by Sol-gel Route	749
Chalcogenide Micro/Nanostructures by Evaporation Condensation Method Swati Raman, Ravi K. Kumar and M. Husain	753
Effect of Parasitic Capacitance on DG-HGTFET and Its Influence on Device RF Performance	757
Section E	
Part VII Optoelectronics	
Optimizing the Optical Properties of ZnO Nanoparticles with Al Doping A. N. Mallika, A. Ramachandra Reddy, K. SowriBabu and K. Venugopal Reddy	763
An Accurate Measurement of Carrier Concentration in an Inhomogeneous  GaN Epitaxial Layer from Hall Measurements	767
Effect of Substrate Temperature Variation and Tartarization on micro-Structural and Optical Properties of Pulsed DC Sputtered Hydrogenated ZnO: Al Films	771

Contents xxiii

Single Crystalline Films of Zinc Oxide for Nanorod Applications	775
Calculation of Direct E <sub>0</sub> Energy Gaps for III–V–Bi Alloys Using Quantum Dielectric Theory	779
Transport of Nitrogen Atoms During the Liquid Phase Epitaxial  Growth of InGaAsN	783
Laser Assisted Surface Photovoltage Spectroscopy: A New Tool for an Accurate Determination of the Bandgap of Semiconductor Epitaxial Layers	787
Influence of Lateral Current Spreading on the Characteristics of High Fill Factor Mesa-Stripe Laser Diode Arrays	791
Voltage Modulated Electroluminescence and Forward Bias Impedance Characteristics of Light Emitting Semiconductor Devices	795
Enhanced Hole Transport in Polyfluorene Polymer by Using Hole Injection Layer	799
Study of Phase Matching Schemes in PPLN for THz Generation	803
Low Temperature Growth of GaN Epitaxial Layer on Sapphire (0001)  Substrate by Laser Molecular Beam Epitaxy Technique	807
Pitch Polishing of Semiconductor Optical Materials Using Continuous Iterative Interferrogram Analysis  Neeraj Pandey, K. K. Pant, S. Mishra, L. M. Pant and A. Ghosh	811
Optical Spectroscopic Studies on Mono-Layer MoS <sub>2</sub>	813
Fabrication of n-ZnO/p-GaAs Heterojunction and Prediction of Its Luminescence Based on Photoluminescence Study	815
Varying Photoconductivity of ZnO as a Function of Annealing Temperature Pranab Biswas and P. Banerji	819

xxiv Contents

Effect of Packing Density on Crosstalk in On-chip Optical Interconnects Prativa Agarwalla and N. R. Das	823
Observation of Low Mobility Electron in Vacancy Doped  LPE Grown HgCdTe	827
Observation of Over-Layer Deposition on HgCdTe Epilayers Grown by Vertical dipping Liquid Phase Epitaxy	829
Preeti Garg, S. A. Hashmi and R. K. Sharma  A Multi-Scale Approach to Wavefunction Engineering of Subdimensional Quantum Semiconductor Structures	833
Synthesis of Cubic Indium Oxide Thin Film by Microwave Irradiation  Ruchi Srivastva, K. Ibrahim and C. S. Yadav	841
Growth of ZnO Nanorod on Flexible Polyethylene Terephthalate Substrate by Chemical Bath Deposition and Microwave Method	845
<b>Bi Incorporation in GaSbBi Films Grown by Liquid Phase Epitaxy</b> S. K. Das, T. D. Das and S. Dhar	847
Study of Optical Parameters of the Thin Films of Se <sub>100-x</sub> Hg <sub>x</sub> with  Laser Irradiation	849
Photo-Induced Inverse Spin Hall Effect in Au/InP Hybrid Structure	855
MBE Growth of $Hg_{1-x}Cd_xTe$ on Cadmium Zinc Telluride Substrates Arun Kumar Garg, Shiv Kumar, Arun Tanwar, S. S. Rana, S. Tyagi and Vikram Dhar	859
Effect of Growth Temperature on Properties of CdZnO Thin Films	865
An Intense Green Emission From ZnO Nanoparticles Coated with MgO K. Sowri Babu, A. Ramachandra Reddy and K. Venugopal Reddy	869
Laser Molecular Beam Epitaxy Growth of GaN Layer on Sapphire (0001) Under Various Process Conditions	873
Hg/Cd Interdiffusion in Thin CdTe Film on HgCdTe Epilayer	877
Characterization of $InP_{1-x}Bi_x$ Alloy Grown by Liquid Phase Epitaxy T. D. Das	879

Contents xxv

Modeling Current Voltage Characteristics of MWIR HgCdTe Diodes at High Reverse Bias Voltage	881
Vanya Srivastav, Navneet Kaur Saini, L. Sareen, R. K. Bhan and R. K. Sharma	001
Growth and Characterization of Screen-Printed Zinc Sulpho Selenide Composite Thin Layer for Solar Cell Buffer Layer Application	885
Part VIII Organic Electronics	
Mixed Ligand Orange Emitter Zinc Complex for Organic Light	001
Emitting Diodes	891
Effect of Slow Traps on Capacitance–Voltage Measurement	895
Bluish-Green Light Emitting Zinc Complex for OLED Application Kapoor Singh, Akshaya Kumar Palai, Amit Kumar and Ishwar Singh	899
Variable Range Hopping Transport in Polypyrrole Composite Films Manish Taunk and Subhash Chand	903
Low Voltage Pentacene Organic Field Effect Transistors with High-K Gate Dielectric	905
Engineering the Optical Properties of insitu Polymerized poly (o-toluidine/ $V_2O_5$ ) Composites	907
Surface Morphology of Pentacene Thin Film	911
Influence of Deposition Rate on Morphology and Optical Properties of Alq <sub>3</sub> , Used as Emitter in OLEDs	913
Part IX Display and Lightening	
An Energy Efficient and High Color Rendering Index Candle Light-Style Organic Light Emitting Diode for Illumination	919
Design and Fabrication of Computer Generated Hologram for Virtual Projection of a Reticle Pattern	923

xxvi Contents

An OFDMA PHY System on Chip Design Methodology	925
Physical and Electrical Characterisation of 3C-SiC and 4H-SiC for	
Power Semiconductor Device Applications	929
M. R. Jennings, C. A. Fisher, S. M. Thomas, Y. Sharma,	
D. Walker, A. Sanchez, A. Pérez-Tomás, D. P. Hamilton,	
P. M. Gammon, S. E. Burrows, F. Li and P. A. Mawby	
Erratum to: An Intense Green Emission From ZnO Nanoparticles	
Coated with MgO	E1
K. Sowri Babu, A. Ramachandra Reddy and K. Venugopal Reddy	

Part I
VLSI and ULSI Technology

#### Impact of Fin Sidewall Taper Angle on Sub-14nm FinFET Device Performance

Abhisek Dixit<sup>1</sup>, Terence B. Hook<sup>2</sup>, Jeffrey B. Johnson<sup>2</sup>, E. J. Nowak<sup>2</sup> and Kota V. Murali<sup>1</sup>

<sup>1</sup>TCAD and Nanotechnology Group, IBM Semiconductor Research and Development Center, Bangalore, INDIA

<sup>2</sup>IBM Semiconductor Research and Development Center, Burlington, Vermont USA

E-mail: abhdixit@in.ibm.com

Abstract—Recent advances in FinFET technology include fins with tapered sidewalls in addition to conventional vertical sidewall fins. Our 3-D TCAD simulation results suggest that for low to moderately doped fins, vertical sidewall fins have superior electrical performance. Only at extremely high fin doping concentrations could tapered sidewall fins be electrically beneficial.

#### Index Terms—FinFET, sidewall tapering and TCAD.

#### I. INTRODUCTION

Because of the excellent control of short-channel effects, FinFETs have become the main-stream CMOS device in both SOI and bulk flavors [1-3]. SOI FinFETs have improved isolation and simplified processing, but require a more complex starting wafer. Bulk silicon FinFETs use the same starting substrate as planar bulk CMOS but require robust isolation schemes [4] and have more challenging aspect ratio and fill requirements than SOI. Electrical performance of a FinFET is largely dependent on the geometry of the fin. While narrow fins help counter short channel effects, tall fins help reduce device foot print to achieve high drive current density. As the fins are formed using a resist or spacer based dry etch, FinFET process could be made more manufacturing friendly by targeting fins with tapered instead of vertical sidewalls [5].

In this work we have analyzed the electrical impact of fin sidewall taper angle using TCAD simulations of a bulk-Si FinFET. The question we address is: aside from manufacturability, is there any benefit to a tapered fin?

#### II. SIMULATION DETAILS

A FinFET 3-D TCAD simulation structure created using Sentaurus structure editor is shown in Fig. 1 [6]. The device shown in Fig. 1 has gate length (L), fin width (D) and fin height (H) as 25nm, 10nm and 25nm respectively. The cross-section through the fin of this device is shown in Fig. 2. It can be imagined from Fig. 2 that in the case of fins with tapered sidewalls, less topography will be encountered during all the subsequent process steps, such as dielectric backfill, spacer etch, and gate fill. Comparing Fig. 2(A) and 2(B) it can be seen that while the fin with vertical sidewalls (taper angle TA=0) has the same width D all through the height H, width of the tapered fin (TA=15) is D only at the middle of the fin height. The simulated tapered fin is narrow on the top and wide at the bottom. Typical process steps followed to create a FinFET structure, such as in Fig. 1 are listed in Table 1. DC electrical simulations were performed using IBM device simulator FIELDAY [7]. For this work we utilized a linear drain bias of 50mV, supply voltage (Vdd) of 0.8V and gate overdrive (Vod), where applicable, of 0.7V.

The current generation of FinFETs relies on metal gate work function for threshold voltage (Vt) adjustment. A technology is comprised of various device flavors required for different applications such as low Vt, regular Vt, high Vt-FETs etc. As it is cumbersome to employ multiple work function gate materials; hence despite known disadvantages [4], fin doping is used for Vt adjustment with a single work function gate. In this work we have explored various fin doping concentrations (Nch) to cover the range of applications.

#### III. RESULTS & DISCUSSIONS

The subthreshold swing (SS) is shown as a function of the fin sidewall taper angle in Fig. 3. It can be seen from Fig. 3 that the SS at zero taper angle decreases with increasing Nch. We attribute this to the increase in effective channel length (Leff) with increasing Nch. For tapered fins (see Fig. 2(B)). Nch controls Vt more effectively in the wider bottom portion of the fin as compared to the narrow top region. Consequently, as Nch increases, Vt of the fin bottom is higher than the top of the fin. In the extreme case, this makes the top portion of the fin determine short channel effects (SCE) of the device. Since the top portion of the fin is narrow where short channel control is better, SS shows slight improvement. Similar trend is observed in Fig. 4, where another short channel parameter DIBL is plotted as a function of the fin taper angle. The net result of SCE can be seen in Fig. 5, where representative subthreshold leakage (Ioff) is plotted as a function of the fin taper angle. Weak SS and DIBL changes seen from previous Fig. 3 and 4, do not seem to impact Ioff enough to explicitly show up on the semi-log plot in Fig. 5. However, there is a small decrease in Ioff of the highly doped fins as taper angle increases.

The impact of fin doping and sidewall taper angle on carrier transport through the channel can be seen from Fig. 6, where linear drain current is plotted as a function of the taper angle. It can be seen from Fig. 6 that Iodlin decreases as both fin doping and taper angle increase. Since Iodlin is simulated at a fixed overdrive, this Iodlin decrease can not be explained by change in Vt. Representative series resistance is plotted in Fig. 7 as a function of taper angle. It can be seen from Fig. 7 that Rodlin increases with increase in taper angle and fin doping. As blanket type fin implant, much like well implant in planar bulk CMOS, is used for doping the fin, background doping in S/D regions also increases along with fin doping. This leads to decrease in S/D doping with increase in fin doping, consequently increasing Rodlin. However, increase in Rodlin with increase in taper angle for highly doped fin is due to narrow low-Vt top portion of the fin being more effective than the wider high-Vt bottom part of the fin. Thus for highly doped and tapered fins, current predominantly flows in the top narrow portion of the fin, encountering higher sheet resistance due to narrow S/D extension regions which explains increase in Rodlin with taper angle. Effective drain current leff is plotted as a function of taper angle in Fig. 8. It can be seen from Fig. 8 that Ieff follows the Iodlin and Rodlin trends shown in Fig. 6 and 7. Representative intrinsic transistor performance is shown in Fig. 9, where representative Ioff is plotted as a function of Ieff. It can be seen from Fig. 9 that at a constant Ioff=100nA/um, fin without tapered sidewalls has the highest Ieff. With increase in fin doping, the disadvantage in leff of tapered fins is mitigated. However, within usable range of fin doping concentrations up to 8e18 cm<sup>-3</sup>, fin sidewall tapering is still undesirable.

#### CONCLUSIONS

The impact of fin sidewall tapering on electrical performance of a bulk Si FinFET is reviewed. It is observed that the device with low-doped, vertical fin sidewalls achieves the best Ieff performance, while fin sidewall tapering could be beneficial in SCE, but only at extremely high fin doping concentrations.

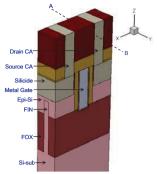


FIG 1: FinFET 3-D simulation structure. A cross-section along the line A-B is shown in FIG 2.

Serial No.	Process module	Purpose
1	FIN	Litho and patterning of fins
2	Gate	Litho and patterning of dummy gates
3	Spacer I	Spacer to protect fin channel during Si-epitaxy
4	Si/SiGe Epi	Epitaxial growth of Si/SiGe on fin S/D regions
5	Spacer 2	Spacer to protect S/D extensions
6	Deep S/D implants and activation	Deep S/D implants and activation anneals
7	RMG	Replacement metal gate process
8	MOL: TS, CA	Mid of the line flow, trench Silicide process and deposition of Tungsten to form contacts to S/D and gates
9	BEOL: V0, M1, V1, M2,	Back end of the line flow to form various levels of metallization

TABLE 1: Process modules in a generic FinFET flow.

(uA/um) 30

Nch=5e17 cm<sup>-3</sup>

Nch=8e18 cm<sup>-3</sup>

Taper Angle (deg)

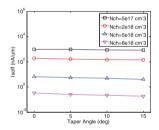


FIG 5: Representative Ioff at Vgs=Vod and Vgs=0 and Vds=Vdd vs. fin Vds=50mV vs. fin sidewall sidewall taper angle.

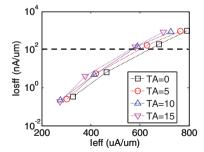


FIG 9: Representative Ioff as a function of Ieff, Nch increases from right to left for each taper angle (TA).

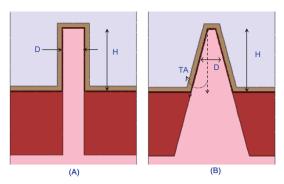
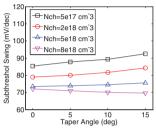


FIG 2: Simulated Fin cross-sections. D, H and TA are finwidth, height and sidewall taper-angle respectively: (A) 0 degree (B) 15 degree.



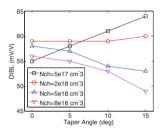
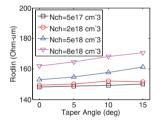


FIG 3: Subthreshold-swing at Vds=Vdd vs. fin sidewall taper angle.

FIG 4: DIBL vs. fin sidewall taper angle.



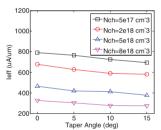


FIG 7: Rodlin at Vgs=Vod Fl and Vds=50mV vs. fin ta sidewall taper angle.

FIG 8: Ieff vs. fin sidewall taper angle.

#### IV. REFERENCES

- P. Hashemi et al, "High-Performance Si1-xGex Channel on Insulator Trigate PFETs Featuring an Implant-Free Process and Aggressively-Scaled Fin and Gate Dimensions", Symp. VLSI Tech., 2013.
   R. Brian et al, "A 22nm High Performance Embedded DRAM SoC
- [2] R. Brian et al, "A 22nm High Performance Embedded DRAM SoC Technology Featuring Tri-gate Transistors and MIMCAP COB", Symp. VLSI Tech., 2013.
- [3] T. Hook, "Fully Depleted Devices for Designers: FDSOI and FinFETs," Custom Integrated Circuits Conference, 2012.
- [4] T. Hook, "FinFET Isolation Considerations and Ramifications: Bulk vs SOI," Advanced Substrate News, April 2013.
- [5] Auth C. et al, "A 22nm high performance and low-power CMOS technology featuring fully-depleted tri-gate transistors, self-aligned contacts and high density MIM capacitors", Symp. VLSI Tech., 2012.
- [6] Sentaurus Structure Editor, Version D-2010.03, Synopsys Inc., March 2010
- M. Ieong et al., "Technology Modeling for Emerging SOI Devices", SISPAD 2002, pp. 225-230, 2002.

# $\label{eq:capacitance-Voltage measurement of SiO_2/GeO_xN_y\ gate\ stack\ on\ surface\ passivated \\ germanium$

Anil G. Khairnar\*, Vilas S. Patil and Ashok M. Mahajan\*

Department of Electronics, School of Physical Sciences, North Maharashtra University Jalgaon, Maharashtra, India-425001

\*E-mail: agkhairnar@gmail.com, ammahajan@nmu.ac.in

Abstract-Germanium (Ge) based MOS transistors is possible alternative to silicon based MOS transistors due to high mobility of carriers in Ge. Extensive research is going on for fabrication of high mobility MOS devices worldwide. Here, we have studied the c-v characteristics of Ge based surface passivated MOS structure such as dielectric constant of gate stack, effective oxide charges, density of interface charges at semiconductor oxide interface etc. The interface trap density extracted from the C-V/G-V measurement showed the lowest interface trap density of  $7.82 \times 10^{11} \text{cm}^2 \text{eV}^{-1}$ . The minimum leakage current density for  $SiO_2/Ge_xON_y$  gate dielectric stack is  $1.35 \times 10^{-7} \text{Acm}^{-2}$  at gate bias of IV.

Index Terms — Germanium, Passivation, Sputtering,  $SiO_2$ ,  $D_{it}$ .

#### I. INTRODUCTION

Germanium has attracted great interest as a candidate channel material for nanoscale complementary metal oxide semiconductor (CMOS) devices. It has the highest hole mobility amongst all identified semiconductor materials, being the principal candidate to substitute Si in future PMOS devices [1-2]. However, there are many difficulties in realizing germanium CMOS technology associated with the different physical and chemical properties of Ge compared to Si [3-4]. Unlike SiO<sub>2</sub> thermally grown on Si, GeO2 is thermally unstable in processing temperatures usually employed in device fabrication [5]. It is well known fact that GeO2 is water soluble, hygroscopic and exhibits poor thermal stability therefore controlling germanium interfaces is essential for future generation devices. In sight of these characteristics, an apparently trivial solution is the replacement of the Ge native oxide by another dielectric material with intrinsically better physical properties. [6-9]. The fabrication of high speed MOS devices based on Ge requires a high quality gate oxide as an insulating layer and many recent studies on this topic are being reported [10-16]. However, deposition of SiO<sub>2</sub> layer onto germanium is rather rarely reported in the literature. In this work, we focused on formation of ultrathin GeO<sub>x</sub>N<sub>v</sub> layer and investigated the effects of this interface layer on dielectric/Ge interface passivation and SiO2 as dielectric.

In this paper, we report the formation of  $GeO_xN_y$  interfacial layer for the high-k gate stacks. Thermally grown  $GeO_xN_y$  layer has been formed at 550°C for passivation of Ge surface. Silicon dioxide has been deposited as a gate dielectric through RF sputtering. The RF sputtering have

been used to attain good quality of thin films as reported previously [16]. The post-deposition annealing of the samples is performed inside the RTP system in nitrogen ambient. The process of annealing refines grains, induces softness and removes strains and stresses from the film. XRD and ellipsometer were used to characterize the  $\text{GeO}_x\text{N}_y$  layer. MOS capacitors have been fabricated using  $\text{GeO}_x\text{N}_y$  with a sputtered silicon dioxide (SiO2) on top of it followed by growing Pt metal layer as gate contact. The second section of this paper explains the experimental part. The results are discussed in third section and fourth section concludes the paper.

#### II. EXPERIMENTAL DETAILS

The 2" p-type Ge (100) substrates were used for the fabrication of Pt/SiO<sub>2</sub>/GeO<sub>x</sub>N<sub>y</sub>/Ge MOS structures. The substrates were rinsed in 2% HF and de-ionized water alternately for several times, followed by blowing dry with N<sub>2</sub>. Following that, annealing in a NH<sub>3</sub> ambient was performed inside a RTP chamber at a constant temperature of 550 °C for four minutes. Substrates were then transferred to the sputtering chamber for the deposition of SiO<sub>2</sub> thin films. Post deposition annealing (PDA) was performed in N2 ambient at 500 °C for 60 s at atmospheric pressure using rapid thermal annealing. Thickness of the GeON/SiO<sub>2</sub> bilayer dielectric stack was measured to be in the range of 27.69-28.57 nm. The thickness of interfacial GeON layer was approximately 5.52-5.79 nm. The refractive index value for dielectric stack was found to be in the range of 1.46-1.49. To study the electrical properites Platinum metal was deposited as top electrode on SiO2 thin films through shadow mask with electrode area of  $12.56 \times 10^{-4} \text{cm}^2$  by using metal sputtering system (Nordiko) at base pressure of  $2.3 \times 10^{-5}$  mbar where substrate was kept at room temperature. An ohmic contact was formed on backside of Ge substrate to form MOS structures by thermally evaporating the Al metal. These fabricated Pt/SiO<sub>2</sub>/GeO<sub>x</sub>N<sub>v</sub>/Ge MOS structures were post metallization annealed (PMA) at 450 °C for 20 min using forming gas (90%N<sub>2</sub>, 10%H<sub>2</sub>) ambient. The structural characterization of annealed SiO2 films was carried out by using the ellipsometer (Philips SD 1000), XRD (BRUKER Model D8 ADVANCE) and AFM. The electrical properties were studied by capacitance-voltage (C-V) and Current voltage, I-(semiconductor characterization system measurements of fabricated MOS structures.